Bulletin PD-20300 rev. D 07/04

International
IOR Rectifier

30CTQ060
30CTQ060S
30CTQ060 -1

SCHOTTKY RECTIFIER

30 Amp

$I_{F(AV)}$ = 30Amp
V_R = 50 - 60V

Major Ratings and Characteristics

Characteristics		30CTQ	Units
$I_{F(AV)}$	Rectangular waveform	30	A
V_{RRM}		50 - 60	V
I_{FSM}	@ tp = 5 µs sine	1000	A
V_F	@15 Apk, T_J = 125°C (per leg)	0.56	V
T_J	range	- 55 to 150	°C

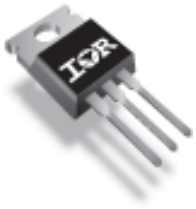
Description/ Features

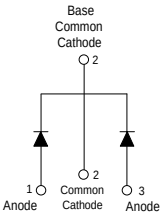
This center tap Schottky rrectifier has been optimized for very low forward voltage drop, with moderate leakage. The proprietary barrier technology allows for reliable operation up to 150° C junction temperature. Typical applications are in switching power supplies, converters, free-wheeling diodes, and reverse battery protection.

- 150° C T_J operation
- Center tap configuration
- Very low forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability

Case Styles

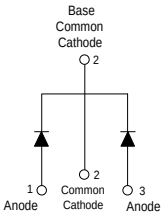
30CTQ...





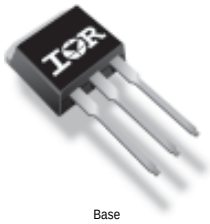
TO-220

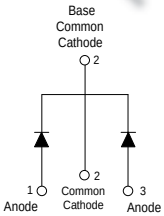
30CTQ... S



D^2PAK

30CTQ... -1





TO-262

Voltage Ratings

	Part number	30CTQ050	30CTQ060
V_R	Max. DC Reverse Voltage (V)	50	60
V_{RWM}	Max. Working Peak Reverse Voltage (V)		

Absolute Maximum Ratings

	Parameters	Values	Units	Conditions	
$I_{F(AV)}$	Max. Average Forward (Per Leg)	15	A	50% duty cycle @ T_C = 105°C, rectangular wave form	
	Current * See Fig. 5 (Per Device)	30			
I_{FSM}	Max. Peak One Cycle Non-Repetitive	1000	A	5µs Sine or 3µs Rect. pulse	Following any rated load condition and with rated V_{RRM} applied
	Surge Current (Per Leg) * See Fig. 7	260		10ms Sine or 6ms Rect. pulse	
E_{AS}	Non-Repetitive Avalanche Energy (Per Leg)	13	mJ	T_J = 25 °C, I_{AS} = 1.50 Amps, L = 11.5 mH	
I_{AR}	Repetitive Avalanche Current (Per Leg)	1.50	A	Current decaying linearly to zero in 1 µsec Frequency limited by T_J max. V_A = 1.5 x V_R typical	

Electrical Specifications

	Parameters	Values	Units	Conditions	
V_{FM}	Max. Forward Voltage Drop (Per Leg) * See Fig. 1 (1)	0.62	V	@ 15A	T_J = 25 °C
		0.82	V	@ 30A	
		0.56	V	@ 15A	T_J = 125 °C
		0.71	V	@ 30A	
I_{RM}	Max. Reverse Leakage Current (Per Leg) * See Fig. 2 (1)	0.80	mA	T_J = 25 °C	V_R = rated V_R
		45	mA	T_J = 125 °C	
$V_{F(TO)}$	Threshold Voltage	0.39	V	T_J = T_J max.	
r_t	Forward Slope Resistance	8.47	mΩ		
C_T	Max. Junction Capacitance (Per Leg)	720	pF	V_R = 5V_{DC} (test signal range 100Khz to 1Mhz) 25°C	
L_S	Typical Series Inductance (Per Leg)	8.0	nH	Measured lead to lead 5mm from package body	
dv/dt	Max. Voltage Rate of Change (Rated V_R)	10000	V/ µs		

(1) Pulse Width < 300µs, Duty Cycle <2%

Thermal-Mechanical Specifications

	Parameters		Values	Units	Conditions
T_J	Max. Junction Temperature Range		-55 to 150	°C	
T_{stg}	Max. Storage Temperature Range		-55 to 150	°C	
R_{thJC}	Max. Thermal Resistance Junction to Case (Per Leg)		3.25	°C/W	DC operation
R_{thJC}	Max. Thermal Resistance Junction to Case (Per Package)		1.63	°C/W	DC operation
R_{thCS}	Typical Thermal Resistance, Case to Heatsink		0.50	°C/W	Mounting surface, smooth and greased (only for TO-220)
wt	Approximate Weight		2 (0.07)	g (oz.)	
T	Mounting Torque	Min.	6 (5)	Kg-cm (lbf-in)	
		Max.	12 (10)		

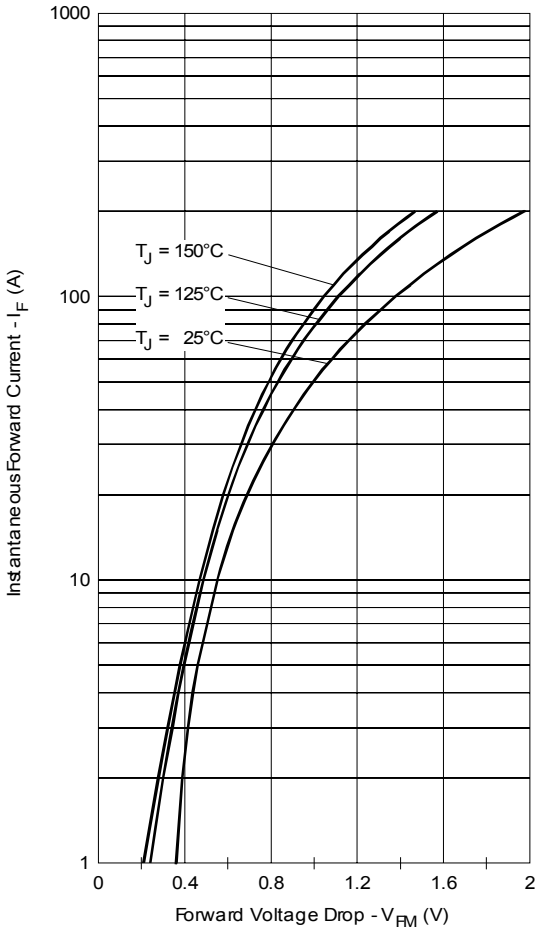


Fig. 1 - Max. Forward Voltage Drop Characteristics (Per Leg)

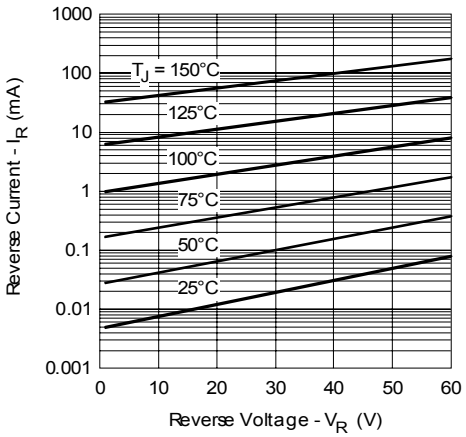


Fig. 2 - Typical Values Of Reverse Current Vs. Reverse Voltage (Per Leg)

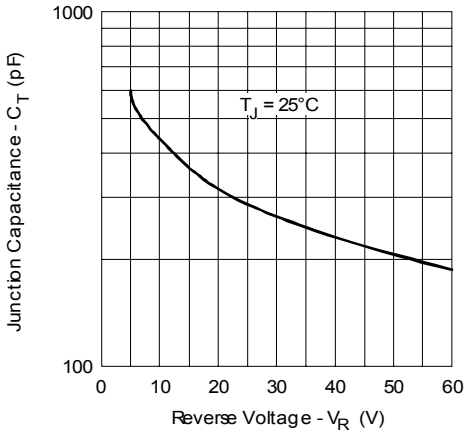


Fig. 3 - Typical Junction Capacitance Vs. Reverse Voltage (Per Leg)

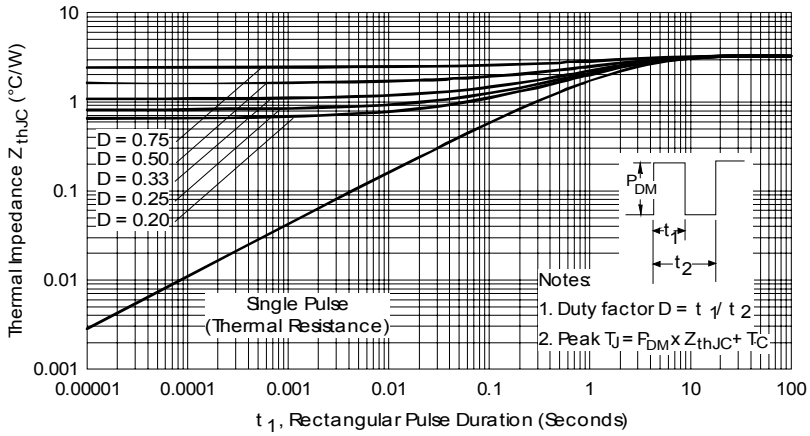


Fig. 4 - Max. Thermal Impedance Z_{thJC} Characteristics (Per Leg)

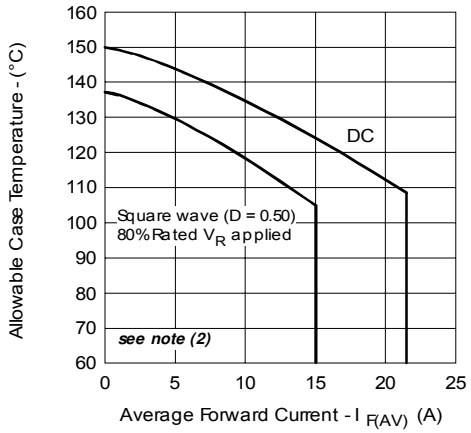


Fig. 5 - Max. Allowable Case Temperature Vs. Average Forward Current (Per Leg)

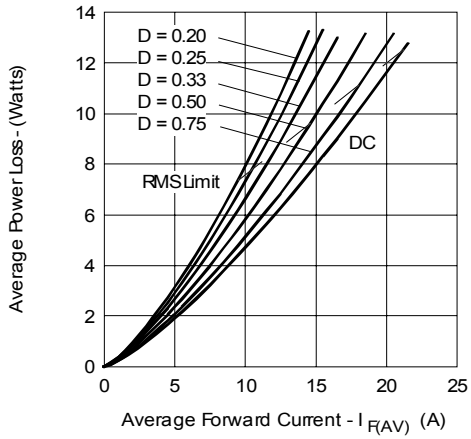


Fig. 6 - Forward Power Loss Characteristics (Per Leg)

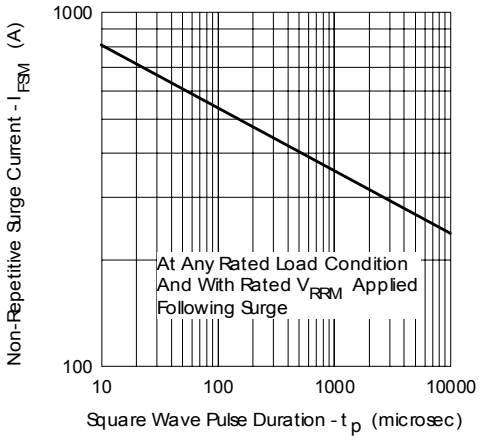


Fig. 7 - Max. Non-Repetitive Surge Current (Per Leg)

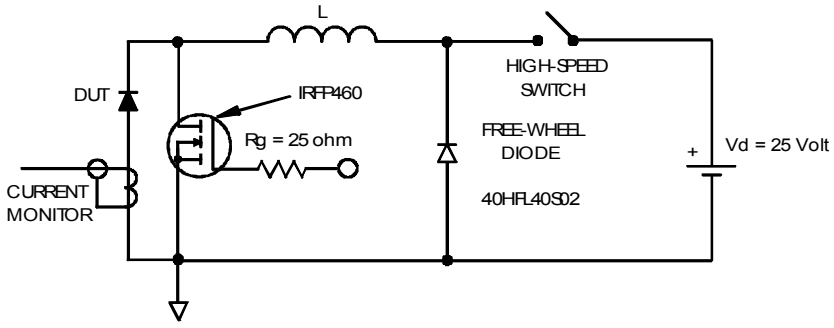
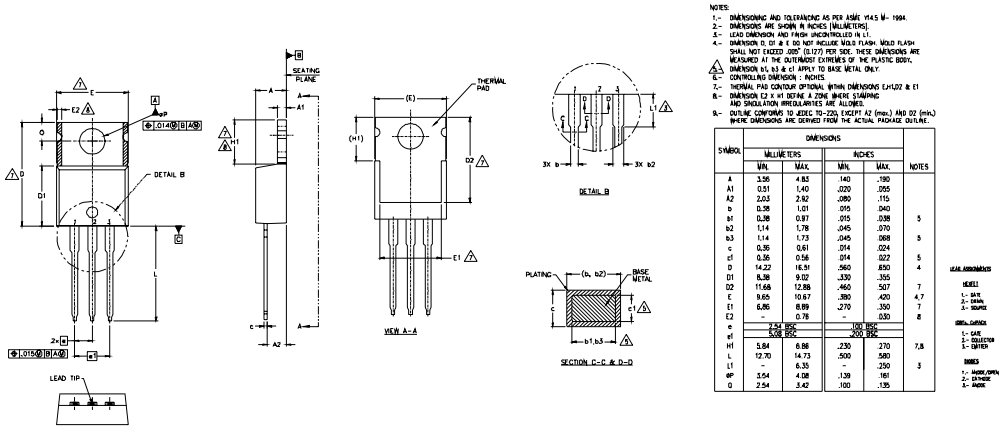


Fig. 8 - Unclamped Inductive Test Circuit

(2) Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$;
Pd = Forward Power Loss = $I_{F(AV)} \times V_{FM} @ (I_{F(AV)} / D)$ (see Fig. 6);
Pd_{REV} = Inverse Power Loss = $V_{R1} \times I_R (1 - D)$; $I_R @ V_{R1} = 10$ V

Outline Table

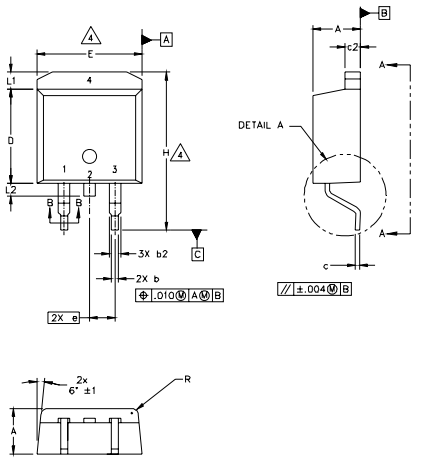


NOTES:
1.- DIMENSIONING AND TOLERANCING AS PER ASME Y14.5 M- 1994.
2.- DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS].
3.- LEAD DIMENSION AND FINISH UNCONTROLLED IN L1.
4.- DIMENSION D, D1 & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
4 DIMENSION b1, b3 & c1 APPLY TO BASE METAL ONLY.
6.- CONTROLLING DIMENSION : INCHES.
7.- THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS E1,H1,D2 & E1.
8.- DIMENSION E2 X H1 DEFINE A ZONE WHERE STAMPING AND SINGULATION IRREGULARITIES ARE ALLOWED.
9.- OUTLINE CONFORMS TO JEDEC TO-220, EXCEPT A2 (max.) AND D2 (min.) WHERE DIMENSIONS ARE DERIVED FROM THE ACTUAL PACKAGE OUTLINE.

SYMBOL	DIMENSIONS				
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	NOTES
A	3.56	4.83	.140	.190	
A1	0.51	1.40	.020	.055	
A2	2.03	2.92	.080	.115	
b	0.38	1.01	.015	.040	
b1	0.38	0.97	.015	.038	5
b2	1.14	1.78	.045	.070	
b3	1.14	1.73	.045	.068	5
c	0.36	0.61	.014	.024	
c1	0.36	0.56	.014	.022	5
D	14.22	16.51	.560	.650	4
D1	8.38	9.02	.330	.355	
D2	11.68	12.88	.460	.507	7
E	9.65	10.67	.380	.420	4,7
E1	6.86	8.89	.270	.350	7
E2	-	0.76	-	.030	8
e	2.54 BSC		.100 BSC		
e1	5.08 BSC		.200 BSC		
H1	5.84	6.86	.230	.270	7,8
L	12.70	14.73	.500	.580	
L1	-	6.35	-	.250	3
øP	3.54	4.08	.139	.161	
Q	2.54	3.42	.100	.135	

LEAD ASSIGNMENTS
HEXFET
1.- GATE
2.- DRAIN
3.- SOURCE
IGBTs, CoPACK
1.- GATE
2.- COLLECTOR
3.- EMITTER
DIODES
1.- ANODE *
2.- CATHODE
3.- ANODE

Conform to JEDEC outline TO-220AB



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
4 DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
5. CONTROLLING DIMENSION: INCH.

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	.160	.190	
A1	0.00	0.254	.000	.010	
b	0.51	0.99	.020	.039	
b1	0.51	0.89	.020	.035	4
b2	1.14	1.78	.045	.070	
c	0.38	0.74	.015	.029	
c1	0.38	0.58	.015	.023	4
c2	1.14	1.65	.045	.065	
D	8.51	9.65	.335	.380	3
D1	6.86		.270		
E	9.65	10.67	.380	.420	3
E1	6.22		.245		
e	2.54 BSC		.100 BSC		
H	14.61	15.88	.575	.625	
L	1.78	2.79	.070	.110	
L1		1.65		.065	
L2	1.27	1.78	.050	.070	
L3	0.25 BSC		.010 BSC		
L4	4.78	5.28	.188	.208	
m	17.78		.700		
m1	8.89		.350		
n	11.43		.450		
o	2.08		.082		
p	3.81		.150		
R	0.51	0.71	.020	.028	
θ	90°	93°	90°	93°	

LEAD ASSIGNMENTS

HEXFET

1.- GATE
2, 4.- DRAIN
3.- SOURCE

IGBTs, CoPACK

1.- GATE
2, 4.- COLLECTOR
3.- EMITTER

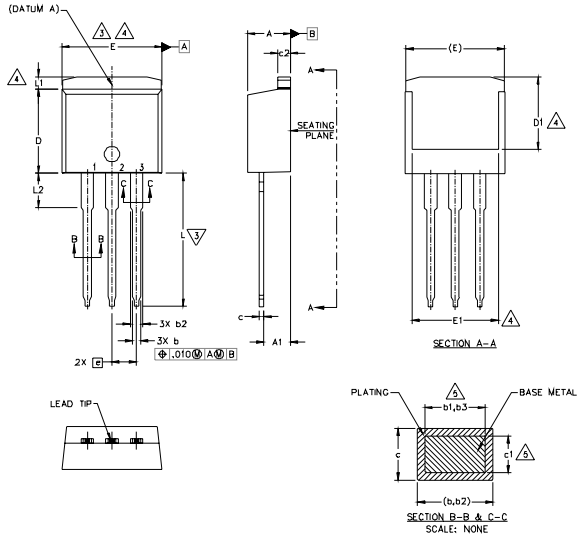
DIODES

1.- ANODE *
2, 4.- CATHODE
3.- ANODE

* PART DEPENDENT.

Conform to JEDEC outline D^2Pak (SMD-220)
Dimensions in millimeters and (inches)

Outline Table



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
4. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSION E, L1, D1 & E1.
5. DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
6. CONTROLLING DIMENSION: INCH.
7.– OUTLINE CONFORM TO JEDEC TO–262 EXCEPT A1(max.), b(min.) AND D1(min.) WHERE DIMENSIONS DERIVED THE ACTUAL PACKAGE OUTLINE.

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	.160	.190	
A1	2.03	3.02	.080	.119	
b	0.51	0.99	.020	.039	
b1	0.51	0.89	.020	.035	5
b2	1.14	1.78	.045	.070	
b3	1.14	1.73	.045	.068	5
c	0.38	0.74	.015	.029	
c1	0.38	0.58	.015	.023	5
c2	1.14	1.65	.045	.065	
D	8.38	9.65	.330	.380	3
D1	6.86	–	.270	–	4
E	9.65	10.67	.380	.420	3,4
E1	6.22	–	.245		4
e	2.54 BSC		.100 BSC		
L	13.46	14.10	.530	.555	
L1	–	1.65	–	.065	4
L2	3.56	3.71	.140	.146	

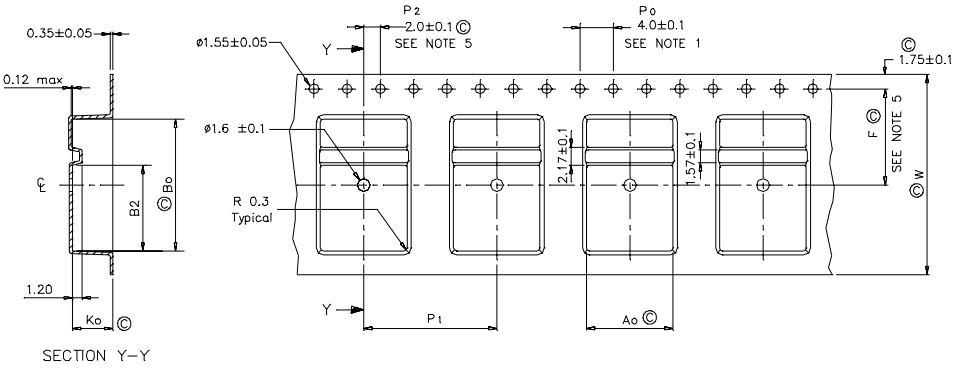
LEAD ASSIGNMENTS

HEXFET
1.– GATE
2.– DRAIN
3.– SOURCE
4.– DRAIN

IGBTs, CoPACK
1.– GATE
2.– COLLECTOR
3.– EMITTER
4.– COLLECTOR

Modified JEDEC outline TO-262
Dimensions in millimeters and (inches)

Tape & Reel Information



Ao	10.50 +/– 0.1
Bo	15.80 +/– 0.1
B2	10.25 +/– 0.1
Ko	4.90 +/– 0.1
F	11.50 +/– 0.1
P1	16.00 +/– 0.1
W	24.00 +/– 0.3

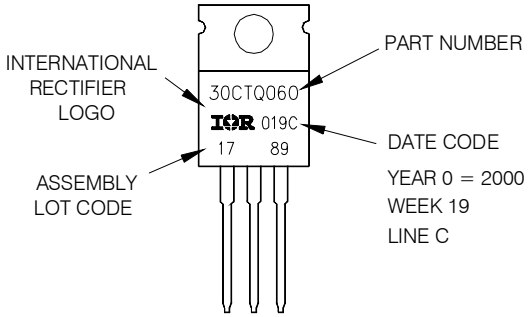
NOTES:
1.0 10 SPROCKET HOLE PITH CUMULATIVE TOLERANCE ±.02
2.0 CAMBER NOT TO EXCEED 1mm In 100mm
3.0 MATERIAL: CONDUCTIVE BLACK STYRENIC ALLOY
4.0 Ko MEASURED FROM A PLANE ON THE INSIDE BOTTOM OF THE POCKET TO THE TOP SURFACE OF THE CARRIER
5.0 MEASURED FROM CENTRELINE OF SPROCKET HOLE TO CENTRELINE OF POCKET
6.0 VENDOR: (OPTIONAL)
7.0 MUST ALSO MEET REQUIREMENTS OF EIA STANDAR #EIA–481A TAPING OF SURFACE MOUNT COMPONENTS FOR AUTOMATIC PLACEMENT
8.0 SURFACE RESISTIVITY OF MOLDED MATL. MUST MEASURE LESS OR EQUAL TO 10^6 OHMS PER SQUARE. MEASURED IN ACCORDANCE TO PROCEDURE GIVEN IN ASTM D–257 & ASTM D–991
9.0 TOTAL LENGTH PER REEL MUST BE 45 METERS
10.0 Ⓒ CRITICAL

Dimensions in millimeters and (inches)

Part Marking Information

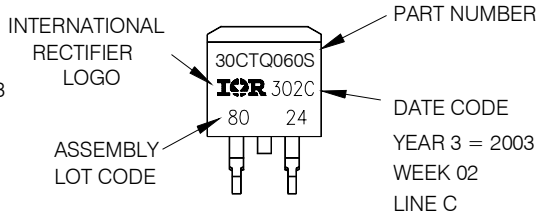
TO-220

EXAMPLE: THIS IS A 30CTQ060
LOT CODE 1789
ASSEMBLED ON WW 19, 2000
IN THE ASSEMBLY LINE "C"



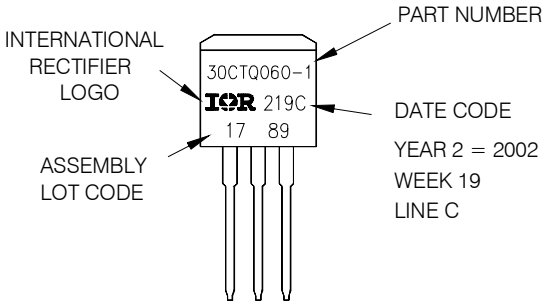
D^2PAK

EXAMPLE: THIS IS A 30CTQ060S
LOT CODE 8024
ASSEMBLED ON WW 02, 2003
IN ASSEMBLY LINE "C"



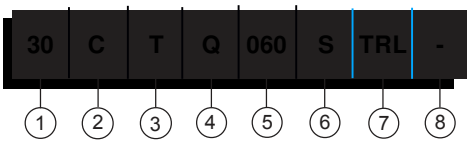
TO-262

EXAMPLE: THIS IS A 30CTQ060-1
LOT CODE 1789
ASSEMBLED ON WW 19, 2002
IN ASSEMBLY LINE "C"



Ordering Information Table

Device Code



1	-	Current Rating (30A)
2	-	Circuit Configuration C = Common Cathode
3	-	T = TO-220
4	-	Schottky "Q" Series
5	-	Voltage Ratings — 050 = 50V, 060 = 60V
6	-	• S = D^2Pak • -1 = TO-262
7	-	• none = Tube (50 pieces) • TRL = Tape & Reel (Left Oriented - for D^2Pak only) • TRR = Tape & Reel (Right Oriented - for D^2Pak only)
8	-	• none = Standard Production • PbF = Lead-Free

Data and specifications subject to change without notice.
This product has been designed and qualified for Industrial Level.
Qualification Standards can be found on IR's Web site.

International
IOR Rectifier

IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105
TAC Fax: (310) 252-7309
07/06

Notice

The products described herein were acquired by Vishay Intertechnology, Inc., as part of its acquisition of International Rectifier's Power Control Systems (PCS) business, which closed in April 2007. Specifications of the products displayed herein are pending review by Vishay and are subject to the terms and conditions shown below.

Specifications of the products displayed herein are subject to change without notice. Vishay Intertechnology, Inc., or anyone on its behalf, assumes no responsibility or liability for any errors or inaccuracies.

Information contained herein is intended to provide a product description only. No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document. Except as provided in Vishay's terms and conditions of sale for such products, Vishay assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of Vishay products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Vishay for any damages resulting from such improper use or sale.

International Rectifier®, IR®, the IR logo, HEXFET®, HEXSense®, HEXDIP®, DOL®, INTERO®, and POWIRTRAIN® are registered trademarks of International Rectifier Corporation in the U.S. and other countries. All other product names noted herein may be trademarks of their respective owners.